

## **Typical Reflow Applications for PRO 1600 Series Reflow Ovens**

- Printed Circuit Board (PCB) assemblies requiring high quality and repeatable results in prototype - medium volumes (depending on PCB size).
- Single or Double Sided PCB's with standard or Pb-Free solders.
- Densely populated, high thermal mass assemblies.
- Components per JEDEC 22-A113 and IPC/JEDEC J-STD-020 standards for Leaded and Pb-Free profiles.
- Solder preforms in an inert atmosphere.
- Bare PCB's to simulate profiles developed for volume production environments.
- Delamination and other quality issues testing on multilayer PCB's.
- Various composite materials for analysis / testing.
- Ceramic substrates to Gold Plated Nickel / Copper housings using preforms in an atmosphere with <50 PPM of Oxygen.
- Copper heatsinks to PCB's using preforms.
- Gold / Tin reflow.
- Temperature preconditioning of IC's while in extruded aluminum tubes.
- Aluminum pins to a metal housing.
- Flex connector to ceramic substrate.
- Surface Mount Devices / Passive Components to ceramic substrate.
- Connector filters with fluxed preforms.
- LED's in production quantities.
- Various solder pastes for analysis in an R&D environment.